

**IN THE CLAIMS:**

1. (Currently Amended) A machine for placing components on a printed circuit board, comprising:

- a transport device for transporting printed circuit boards in an X-direction;
- at least one feeder area with components;
- a Y-slide, which is independently drivable in the X-direction; and
- at least two placement heads on said Y-slide, each of the at least two placement heads being ~~capable of~~ **adapted for** placing components from the at least one feeder area onto the printed circuit board,

wherein each of the at least two placement heads arranged on ~~a particular~~ **said** Y-slide move simultaneously in the X-direction and **each of the at least two placement heads is** ~~are~~ independently drivable in a Y-direction.

2. (Previously presented) The machine as claimed in claim 1, further comprising a plurality of Y-slides, each of which are independently drivable in the X-direction, each of the plurality of Y-slides being provided with at least two placement heads.

3. (Withdrawn) A method of placing components on a printed circuit board by means of a component placement machine comprising:

- in a first period of time, moving a first placement head to a desired X-Y position above a first feeder and, subsequently, picking up a component from the first feeder, moving a second placement head along a Y-slide to a desired Y-position so as to prepare for the placement of a previously picked-up component on the printed circuit board,

- in a second period of time following the first period of time, moving the second placement head to a desired X-Y position above the printed circuit board and, subsequently, placing the component on the printed circuit board,

- in a third period of time following the second period of time, moving the second placement head to a desired X-Y position above a second feeder and, subsequently, picking up a component from the second feeder, moving the first placement head along the Y-slide to a desired Y-position so as to prepare for the placement on the printed circuit board of the component picked up in the first period of time, and

- in a fourth period of time following the third period of time, moving the first placement head to a desired X-Y position above the printed circuit board and, subsequently, placing the component on the printed circuit board.

4. (Withdrawn) A method of placing components on a printed circuit board by means of a component placement machine comprising:

- in a first period of time, moving a first series of placement heads to a desired X-Y position above a first feeder and, subsequently, simultaneously picking up components from the first feeder, moving a second series of placement heads along one of a multitude of Y-slides to a desired Y-position so as to prepare for the placement on the printed circuit board of previously picked-up components,

- in a second period of time following the first period of time, moving the second series of placement heads to a desired X-Y position above the printed circuit board and, subsequently, placing the components simultaneously on the printed circuit board,

- in a third period of time following the second period of time, moving the second series of placement heads to a desired X-Y position above a second feeder and, subsequently, simultaneously picking up components from the second feeder, moving the first series of placement heads moves along the one of a multitude of Y-slides to a desired Y-position so as to prepare for the placement on the printed circuit board of the components picked up in the first period of time, and

in a fourth period of time following the third period of time, moving the first series of placement heads to a desired X-Y position above the printed circuit board and, subsequently, placing the components simultaneously on the printed circuit board.